



Material Content Data Sheet



Sales Product Name		BAS 70-02L E6327		Issued		24. January 2018		
MA#		MA001789468						
Package		PG-TSLP-2-1		Weight*		0.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.10		1045	
	noble metal	gold	7440-57-5	0.002	0.41		4056	
	inorganic material	silicon	7440-21-3	0.026	4.95	5.46	49512	54613
leadframe	non noble metal	nickel	7440-02-0	0.100	19.41	19.41	194065	194065
wire	noble metal	gold	7440-57-5	0.006	1.13	1.13	11256	11256
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		350	
	organic material	carbon black	1333-86-4	0.004	0.70		7028	
	plastics	epoxy resin	-	0.049	9.49		94866	
	inorganic material	silicondioxide	60676-86-0	0.310	60.03	70.26	600476	702720
leadfinish	noble metal	gold	7440-57-5	0.010	1.87	1.87	18673	18673
plating	noble metal	gold	7440-57-5	0.010	1.87	1.87	18673	18673
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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